Product Change Notification: CAAN-16AAIV996

Date:

25-Sep-2026

Product Category:

8-Bit Microcontrollers

Notification Subject:

CCB 8434 Initial Notice: Qualification of MMT as an additional assembly site for selected AVR32EB28, AVR32LA28, AVR16LA28, PIC16F17556, PIC16F17555, PIC16F17554, PIC16F15256, PIC16F15254, PIC16F15255, PIC16F18054, PIC16F18055, PIC16F18056, ATMEGA1608, ATMEGA808, ATMEGA4808, PIC16F13254, PIC16F13255, PIC16F13256, PIC16F17154, PIC16F18154, PIC16F17155, PIC16F18155, PIC16F17156, PIC16F18156, ATMEGA3208, AVR64EA28, AVR32EA28, AVR16EB28 and AVR16EA28 device families available in 28L SSOP (.209in) package.

Affected CPNs:

CAAN-16AAIV996_Affected_CPN_09252026.pdf
CAAN-16AAIV996_Affected_CPN_09252026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected AVR32EB28, AVR32LA28, AVR16LA28, PIC16F17556, PIC16F17555, PIC16F17554, PIC16F15256, PIC16F15254, PIC16F15255, PIC16F18054, PIC16F18055, PIC16F18056, ATMEGA1608, ATMEGA808, ATMEGA4808, PIC16F13254, PIC16F13255, PIC16F13256, PIC16F17154, PIC16F18154, PIC16F17155, PIC16F18155, PIC16F17156, PIC16F18156, ATMEGA3208, AVR64EA28, AVR32EA28, AVR16EB28 and AVR16EA28 device families available in 28L SSOP (.209in) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (Branch) (MMT)	Yes
Wire Material	CuPdAu	CuPdAu	CuPdAu	No
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	CRM-1064L (PFAS-free)	Yes
Molding Compound Material	G600	G600	G630AY	Yes
Lead-Frame Material	CDA194	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: November 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2026					**>**	**November 2026**				
Work Week	36	37	38	39	40		45	46	47	48	49
Initial PCN Issue Date				X							
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: September 25, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-16AAIV996_Qual Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

AVR32EA28T-I/SS

AVR32EA28T-E/SS

AVR16EB28-E/SS

AVR16EB28-I/SS

AVR16EB28T-I/SS

AVR16EB28T-E/SS

AVR16EA28-E/SS

PIC16F17155-I/SS

PIC16F18155-I/SS

PIC16F17154T-I/SS

PIC16F18154T-I/SS

PIC16F17155T-I/SS

PIC16F18155T-I/SS

PIC16F13255-I/SS

PIC16F13256-I/SS

PIC16F13254T-I/SS

PIC16F13255T-I/SS

PIC16F13256T-I/SS

PIC16F17154-E/SS

PIC16F18154-E/SS

PIC16F17155-E/SS

PIC16F18155-E/SS

PIC16F17154-I/SS

PIC16F18154-I/SS

PIC16F17156-E/SS

PIC16F18156-E/SS

PIC16F17156-I/SS

AVR32EB28-E/SS

AVR32EB28-I/SS

AVR32EB28T-I/SS

AVR32EB28T-E/SS

AVR32LA28-E/SS

AVR16LA28-E/SS

AVR32LA28-I/SS

AVR16LA28-I/SS

AVR32LA28T-I/SS

AVR16LA28T-I/SS

AVR32LA28T-E/SS

AVR16LA28T-E/SS

PIC16F17556-E/SS

PIC16F17555-I/SS

PIC16F17556-I/SS

PIC16F17556T-I/SS

PIC16F17554-E/SS

PIC16F18054-I/SS

PIC16F18055-I/SS

PIC16F18054T-I/SS

PIC16F18055T-I/SS

PIC16F18056-E/SS

PIC16F18056-I/SS

PIC16F18056T-I/SS

ATMEGA1608-XF

ATMEGA1608-XU

ATMEGA1608-XUR

ATMEGA1608-XFR

ATMEGA808-XF

PIC16F17555-E/SS

PIC16F17554-I/SS

PIC16F17554T-I/SS

PIC16F17555T-I/SS

PIC16F15256-E/SS

PIC16F15256-I/SSC01

PIC16F15256-I/SS

PIC16F15256T-I/SSC01

AVR16EA28-I/SS

AVR16EA28T-I/SS

AVR16EA28T-E/SS

PIC16F15256T-I/SS

PIC16F15256T-E/SS

PIC16F15254-E/SS

PIC16F15255-E/SS

PIC16F15254-I/SS

PIC16F15255-I/SS

PIC16F15254T-I/SS

PIC16F15255T-I/SS

PIC16F18054-E/SS

PIC16F18055-E/SS

ATMEGA808-XU

ATMEGA808-XUR

ATMEGA808-XFR

ATMEGA4808-XF

ATMEGA4808-XU

ATMEGA4808-XUR

ATMEGA4808-XFR

PIC16F13254-E/SS

PIC16F13255-E/SS

PIC16F13256-E/SS

PIC16F13254-I/SS

PIC16F18156-I/SS

PIC16F17156T-I/SS

PIC16F18156T-I/SS

ATMEGA3208-XF

ATMEGA3208-XU

ATMEGA3208-XUR

ATMEGA3208-XFR

AVR64EA28-E/SS

AVR64EA28-I/SS

AVR64EA28T-I/SS

AVR64EA28T-E/SS

AVR32EA28-E/SS

AVR32EA28-I/SS



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QUALIFICATION PLAN SUMMARY

PCN#: CAAN-16AAIV996

Date:
September 04, 2026

Qualification of MMT as an additional assembly site for selected AVR32EB28, AVR32LA28, AVR16LA28, PIC16F17556, PIC16F17555, PIC16F17554, PIC16F15256, PIC16F15254, PIC16F15255, PIC16F18054, PIC16F18055, PIC16F18056, ATMEGA1608, ATMEGA808, ATMEGA4808, PIC16F13254, PIC16F13255, PIC16F13256, PIC16F17154, PIC16F18154, PIC16F17155, PIC16F18155, PIC16F17156, PIC16F18156, ATMEGA3208, AVR64EA28, AVR32EA28, AVR16EB28 and AVR16EA28 device families available in 28L SSOP (.209in) package.

Purpose: Qualification of MMT as an additional assembly site for selected AVR32EB28, AVR32LA28, AVR16LA28, PIC16F17556, PIC16F17555, PIC16F17554, PIC16F15256, PIC16F15254, PIC16F15255, PIC16F18054, PIC16F18055, PIC16F18056, ATMEGA1608, ATMEGA808, ATMEGA4808, PIC16F13254, PIC16F13255, PIC16F13256, PIC16F17154, PIC16F18154, PIC16F17155, PIC16F18155, PIC16F17156, PIC16F18156, ATMEGA3208, AVR64EA28, AVR32EA28, AVR16EB28 and AVR16EA28 device families available in 28L SSOP (.209in) package.

CCB No.: 8434

Misc.	Assembly site	MMT
	BD Number	BD-004601-01
	MP Code (MPC)	59F0A4N2XFB3
	Part Number (CPN)	PIC16F17556-E/SS
	MSL information	MSL1
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	47
	Reliability Site	MTAI
Lead-Frame	Paddle size	153x200
	Material	CDA194
	DAP Surface Prep	Bare Cu
	Treatment	Roughening
	Process	Stamped
	Lead-lock	No
	Part Number	10102834
	Lead Plating	Matte tin
Bond Wire	Material	CuPdAu
Die Attach	Part Number	CRM-1064L (PFAS-free)
	Conductive	Yes
MC	Part Number	G630AY
PKG	Package Type	SSOP
	Pin/Ball Count	28
	PKG width/size	209 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5			30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5			30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5			
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5			
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours Electrical test pre and post stress at +25C and hot temp 150C.	45	5	3	150	0	10	MTAI	MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C and 150C. MSL1/260	231	15	3	738	0	15	MTAI	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C and hot temp 150C.	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles Electrical test pre and post stress at hot temp 150C; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.